



RCE / \$ 2800

PTO/SB/30 (01-03)  
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|--|-------------------------------|------------------|
| <b>Request<br/>For<br/>Continued Examination (RCE)<br/>Transmittal</b><br><br>Address to:<br>Commissioner for Patents<br>Mail Stop RCE<br>P.O. Box 1450<br>Alexandria, VA 22313-1450 | <b>Application Number</b>     | 09/731,226       |
|  | <b>Filing Date</b>            | December 4, 2000 |
|  | <b>Examiner Name</b>          | Hunk K. Vu       |
|  | <b>First Named Inventor</b>   | Joshi, Rajeev    |
|  | <b>Art Unit</b>               | 2811             |
|  | <b>Attorney Docket Number</b> | 018865-005100US  |

#11  
RCE  
Robinson  
5/7/03

**This is a Request for Continued Examination (RCE) under 37 CFR 1.114 of the above-identified application.**  
Request for Continued Examination (RCE) practice under 37 CFR 1.114 does not apply to any utility or plant application filed prior to June 8, 1995, or to any design application. See Instruction Sheet for RCEs (not to be submitted to the USPTO) on page 2.

1. **Submission required under 37 CFR 1.114**

a. ☐ Previously submitted

i. ☐ Consider the amendment(s)/reply under 37 CFR 1.116 previously filed on \_\_\_\_  
(Any unentered amendment(s) referred to above will be entered).

ii. ☐ Consider the arguments in the Appeal Brief or Reply Brief previously filed on \_\_\_\_

iii. ☐ Other \_\_\_\_

b. ☒ Enclosed

i. ☒ Amendment/Reply

ii. ☐ Affidavit(s)/ Declaration(s)

iii. ☐ Information Disclosure Statement (IDS)

iv. ☐ Other \_\_\_\_

2. **Miscellaneous**

a. ☐ Suspension of action on the above-identified application is requested under 37 CFR 1.103(c) for a period of \_\_\_\_ months. (Period of suspension shall not exceed 3 months; Fee under 37 CFR 1.17(i) required)

b. ☐ Other \_\_\_\_

3. **Fees** The RCE fee under 37 CFR 1.17(e) is required by 37 CFR 1.114 when the RCE is filed.

a. ☒ The Director is hereby authorized to charge the following fees, or credit any overpayments, to Deposit Account No. 20-1430

i. ☒ RCE fee required under 37 CFR 1.17(e)

ii. ☒ Extension of time fee (37 CFR 1.136 and 1.17)

iii. ☐ Other \_\_\_\_

b. ☐ Check in the amount of \$ \_\_\_\_ enclosed

c. ☐ Payment by credit card (Form PTO-2038 enclosed)

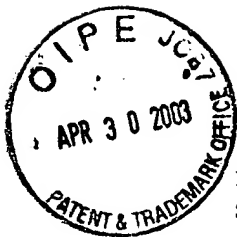
**WARNING: Information on this form may become public. Credit card information should not be included on this form. Provide credit card information and authorization of PTO-2038.**

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| SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT REQUIRED |                |  |                |
|---|----------------|--|----------------|
| <b>Name (Print /Type)</b>                           | Kevin T LeMond | <b>Registration No. (Attorney/Agent)</b> | 35,933         |
| <b>Signature</b>                                    |                | <b>Date</b>                              | April 24, 2003 |

| CERTIFICATE OF MAILING OR TRANSMISSION   |               |             |                |
|--|---------------|-------------|----------------|
| I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, Mail Stop RCE, P.O. Box 1450, Alexandria, VA 22313-1450, or facsimile transmitted to the U.S. Patent and Trademark Office on the date shown below. |               |             |                |
| <b>Name (Print /Type)</b>  | Linda Burgess | <b>Date</b> | April 24, 2003 |
| <b>Signature</b>   |               |             |                |

This collection of information is required by 37 CFR 1.114. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 12 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, Mail Stop RCE, P.O. Box 1450, Alexandria, VA 22313-1450.  
If you need assistance in completing the form, call 1-800-PTO-9199 (1-800-786-9199) and select option 2.



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PATENT  
Attorney Docket No.: 018865-005100US  
Client Ref. No.: 17732-19420

Assistant Commissioner for Patents  
Washington, D.C. 20231

On

April 24, 2003

TOWNSEND and TOWNSEND and CREW LLP

By:

Linda Burgess

#12/B  
Amend B  
Y Rajin  
5/7/03

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of:

Rajeev Joshi et al.

Application No.: 09/731,226

Filed: December 4, 2000

For: PASSIVATION SCHEME FOR  
BUMPED WAFERS

Examiner: Hunk K. Vu

Art Unit: 2811

AMENDMENT

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Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

Applicants request a three-month extension of time from January 24, 2003 to April 24, 2003 and authorize the Commissioner to charge the fee therefor to our deposit account in accordance with the attached Fee Transmittal sheet.

In response to the Final Office Action mailed October 24, 2002, please amend this application as follows:

IN THE CLAIMS:

Please cancel claims 1-3.

Please add the following new claims 6-9.

6. (New) A wafer for use in making a chip device, the wafer comprising:  
a non-passivated die;  
a first titanium layer at non-isolation locations on the die;

B1  
SUB C17